



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-07-11
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	FKQ7*UP04J52	A	BO2A	2017-07-11
Amount	UoM	Unit type	ST ECOPACK Grade	
153.60	mg	Each	ECOPACK® 1	
	Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85x3.9x1.52	16	gull wing	
Comment	PACKAGE: Q7 SO 16 .15 TO JEDEC MS-012; MDF valid for STP08DP05MTR			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	FKQ7*UP04J52				5000000.0	1000003.0
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	1.130	mg	supplier	die	Silicon (Si)	7440-21-3		1.077	mg	953097	7012
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	9735	72
				supplier	metallization	Tungsten (W)	7440-33-7		0.009	mg	7965	59
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	1770	13
				supplier	Passivation	Silicon Oxide	7631-86-9		0.019	mg	16814	124
				supplier	polymer die coating	PIIX1 Gamma-butyrolactone	96-48-0		0.012	mg	10619	78
Leadframe	M-004 Copper and its alloys	48.260	mg	supplier	alloy	Copper (Cu)	7440-50-8		46.813	mg	970017	304772
				supplier	alloy	Iron (Fe)	7439-89-6		1.101	mg	22814	7168
				supplier	alloy	Zinc (Zn)	7440-66-6		0.058	mg	1202	378
				supplier	metallization	Nickel (Ni)	7440-02-0		0.268	mg	5553	1745
M-008 Precious metals	supplier	metallization	Palladium (Pd)	7440-05-3		0.011	mg	228	72			
	supplier	metallization	Gold (Au)	7440-57-5		0.009	mg	186	59			
	supplier	glue	Silver (Ag)	7440-22-4		0.278	mg	749326	1810			
Die attach	M-015 Other organic materials	0.371	mg	supplier	glue	Epoxy Cresol Novolak	29690-82-2		0.091	mg	245283	592
				supplier	glue	1-isopropyl-2,2-dimethyltrimethylene diisobut	6846-50-0		0.002	mg	5391	13
				supplier	wire	Gold (Au)	7440-57-5		0.339	mg	1000000	2207
Bonding wires	M-008 Precious metals	0.339	mg	supplier	wire	Gold (Au)	7440-57-5		0.339	mg	1000000	2207
				supplier	gold compound	Silica, vitreous	60676-86-0		82.800	mg	800000	539063
Encapsulation	M-011 Other inorganic materials	103.500	mg	supplier	mold compound	Epoxy Cresol Novolak	25068-38-6		10.350	mg	100000	67383
				supplier	mold compound	phenol resin	29690-82-2		5.175	mg	50000	33691
				supplier	mold compound	Brominated epoxy resin	40039-93-8		2.070	mg	20000	13477
				supplier	mold compound	Antimony Trioxide	1309-64-4		2.070	mg	20000	13477
				supplier	mold compound	Carbon Black	1333-86-4		1.035	mg	10000	6738